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9-11-02

PATENT APPLICATION *Mullish*

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Shigeyuki UEDA

Application No.: 09/665,663

Filed: September 20, 2000

For: SEMICONDUCTOR CHIP AND METHOD OF PRODUCING THE SAME

Attorney Docket No.: ROH-026

Examiner: W. D. Coleman

Art Unit: 2823

Confirmation No.: 5545

TECHNOLOGY CENTER 2800

SEP - 5 2002

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PRELIMINARY AMENDMENT**BOX RCE**Commissioner for Patents  
Washington, D.C. 20231

Sir:

Prior to examination on the merits after filing the accompanying Request for Continued Examination filed in response to the final Office Action dated May 30, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 1, 6, 8 and 9 without prejudice or disclaimer.

Please amend claims 2, 7 and 10 as set forth below in clean form. Additionally, in accordance with 37 CFR 1.121(c)(1)(ii), amended claim(s) is/are set forth in a marked-up version in the page(s) attached to this Amendment.

*B<sup>1</sup>* 2. (Amended) The semiconductor chip according to claim 11, wherein said semiconductor chip is overlapped with and joined to a surface of another solid device in a state where said surface protective film is opposed to a surface of the solid device.

*B<sup>2</sup>* 7. (Twice Amended) The semiconductor chip according to claim 12, wherein said wire connecting portion is composed of the same material as that for said electrical contact projection.